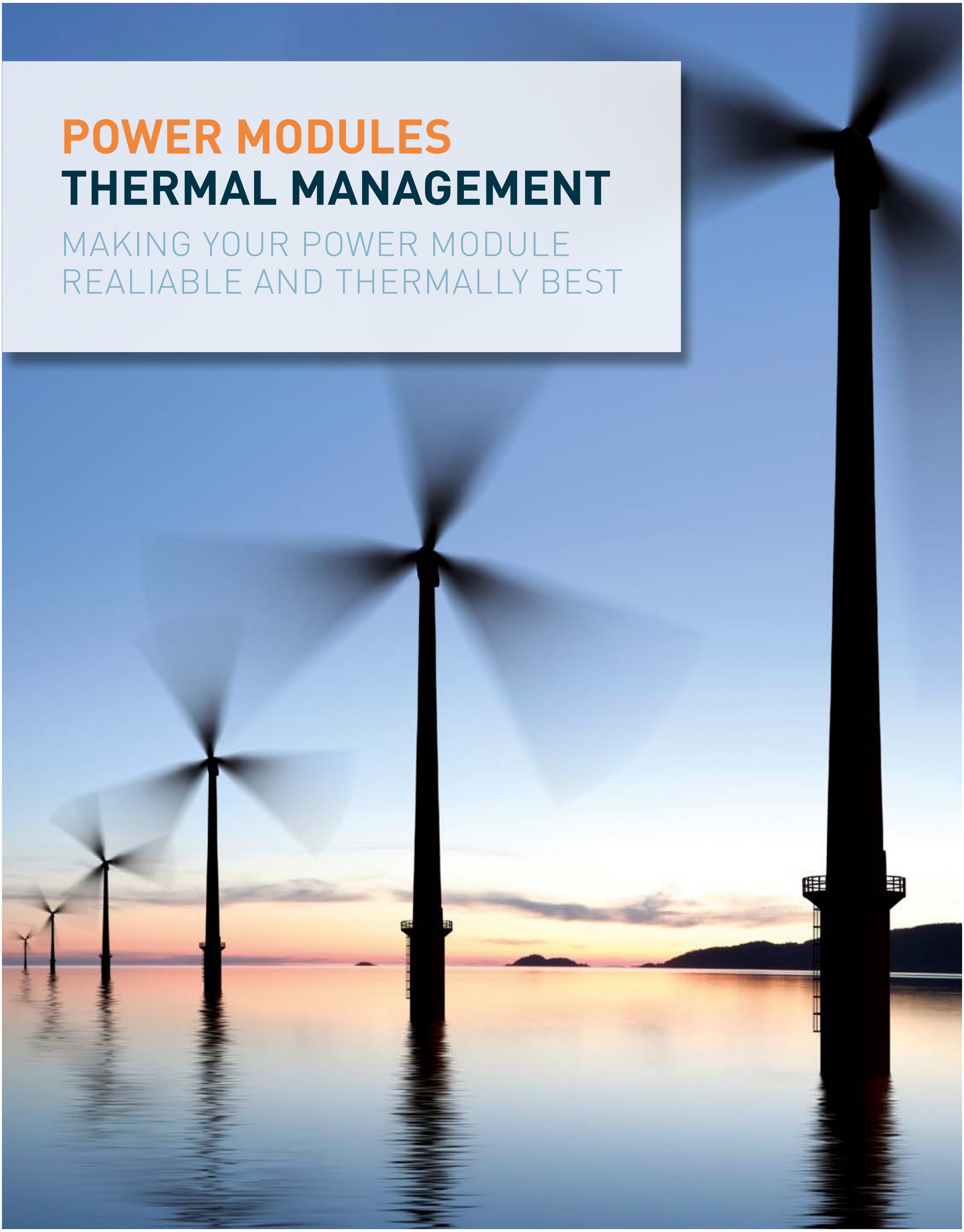
HALA



POWER MODULES
THERMAL MANAGEMENT

MAKING YOUR POWER MODULE REALIABLE AND THERMALLY BEST

APPLICATION

POWER MODULES
THERMAL MANAGEMENT

MAKING YOUR POWER MODULE REALIABLE AND THERMALLY BEST

Release 11 / 2024

MODULAR CONCEPTS

HALA High Performing Contacting Interface Materials

Phase Change films
- ☐ TPC-Y-PC
- ☐ TPC-W-PC
- ☐ TPC-T-AL-CB
- ☐ TPC-R-AL

Graphite foil
- ☐ TFO-S-CB

Graphite foil / pyrolytic
- ☐ TFO-Y-PG
- ☐ TFO-ZS-PG

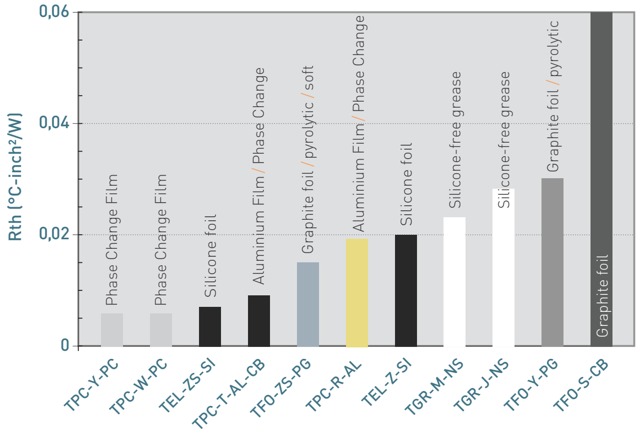
Silicone foil
- ☐ TEL-Z-SI
- ☐ TEL-ZS-SI

Silicone grease
- ☐ TGR-S-SI

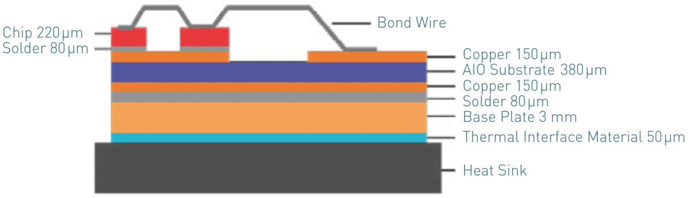
Silicone-free grease
- ☐ TGR-J-NS
- ☐ TGR-M-NS

Module EconoPACK™+

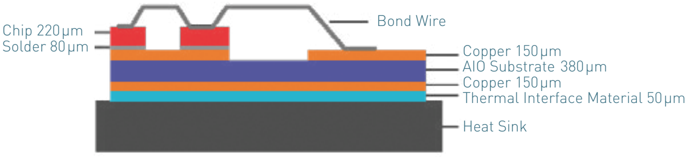
ΔT DATA



CONSTRUCTION DIAGRAM



Typical module configuration with baseplate (Copper)



Typical module configuration without baseplate

Vincotech Module

CREATING
- ☐ Maximum thermal contact
- ☐ Minimized thermal resistance
- ☐ Compensating mechanic tolerances
- ☐ Enhancing efficiency

BENEFITS
- ☐ Increasing long-term reliability
- ☐ Minimizing chip temperatures
- ☐ Homogenizing chip temperatures
- ☐ Pre-applied dry-to-the-touch